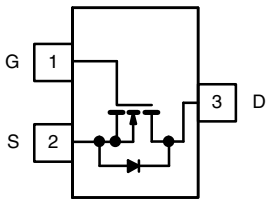
N-Channel 100 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a]	Q_g (Typ.)
100	0.234 at V_{GS} = 10 V	2.3	2.9 nC
	0.267 at V_{GS} = 6 V	2.1	
	0.278 at V_{GS} = 4.5 V	1.7	

TO-236
(SOT-23)



Top View

Si2324DS (D4)*

*** Marking Code**

Ordering Information:
Si2324DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Material categorization:
  For definitions of compliance please see
  www.vishay.com/doc?99912

Pb-free
RoHS COMPLIANT
HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- Load Switch
- LED Backlighting in LCD TVs

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)				
Parameter		**Symbol**	**Limit**	**Unit**
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	2.3	A
	T_C = 70 °C		1.8	
	T_A = 25 °C		1.6[b, c]	
	T_A = 70 °C		1.3[b, c]	
Pulsed Drain Current (t = 300 µs)		I_{DM}	5	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	2.1	
	T_A = 25 °C		1.0[b, c]	
Single Pulse Avalanche Current	L = 0.1 mH	I_{AS}	5	
Single Pulse Avalanche Energy		E_{AS}	1.25	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	2.5	W
	T_C = 70 °C		1.6	
	T_A = 25 °C		1.25[b, c]	
	T_A = 70 °C		0.8[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		**Symbol**	**Typical**	**Maximum**	**Unit**
Maximum Junction-to-Ambient[b, d]	≤ 5 s	R_{thJA}	75	100	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	50	

Notes:
a. Based on T_C = 25 °C.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 5 s.
d. Maximum under steady state conditions is 166 °C/W.

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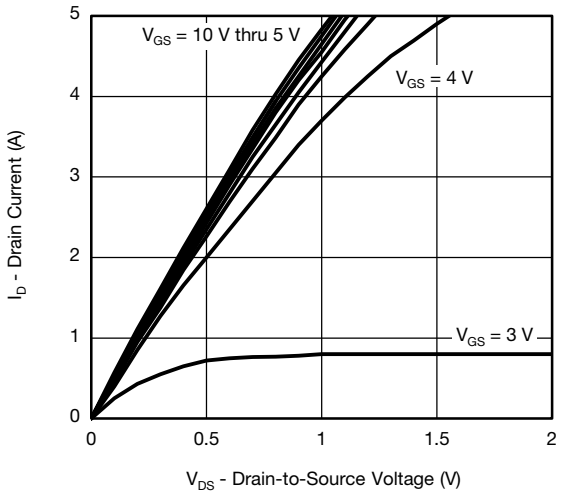
MOSFET SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{DS} = 0 V, I_D = 250 µA	100			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA		105		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5.2		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1.2		2.8	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 100 V, V_{GS} = 0 V			- 1	µA
		V_{DS} = 100 V, V_{GS} = 0 V, T_J = 55 °C			- 10	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ 5 V, V_{GS} = 4.5 V	5			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 1.5 A		0.195	0.234	Ω
		V_{GS} = 6 V, I_D = 1 A		0.222	0.267	
		V_{GS} = 4.5 V, I_D = 0.5 A		0.231	0.278	
Forward Transconductance[a]	g_{fs}	V_{DS} = 20 V, I_D = 1.5 A		2.0		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = 50 V, V_{GS} = 0 V, f = 1 MHz		190		pF
Output Capacitance	C_{oss}			22		
Reverse Transfer Capacitance	C_{rss}			13		
Total Gate Charge	Q_g	V_{DS} = 50 V, V_{GS} = 10 V, I_D = 1.6 A		5.2	10.4	nC
		V_{DS} = 50 V, V_{GS} = 4.5 V, I_D = 1.6 A		2.9	5.8	
Gate-Source Charge	Q_{gs}			0.75		
Gate-Drain Charge	Q_{gd}			1.4		
Gate Resistance	R_g	f = 1 MHz	0.3	1.4	2.8	Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 50 V, R_L = 39 Ω I_D = 1.3 A, V_{GEN} = 4.5 V, R_g = 1 Ω		30	45	ns
Rise Time	t_r			26	39	
Turn-Off Delay Time	$t_{d(off)}$			17	26	
Fall Time	t_f			12	20	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 50 V, R_L = 39 Ω I_D = 1.3 A, V_{GEN} = 10 V, R_g = 1 Ω		6	12	
Rise Time	t_r			10	20	
Turn-Off Delay Time	$t_{d(off)}$			10	20	
Fall Time	t_f			6	12	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			- 2.1	A
Pulse Diode Forward Current[a]	I_{SM}				- 20	
Body Diode Voltage	V_{SD}	I_S = 1.3 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 1.3 A, dI/dt = 100 A/µs, T_J = 25 °C		22	33	ns
Body Diode Reverse Recovery Charge	Q_{rr}			21	32	nC
Reverse Recovery Fall Time	t_a			16		ns
Reverse Recovery Rise Time	t_b			6		

Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

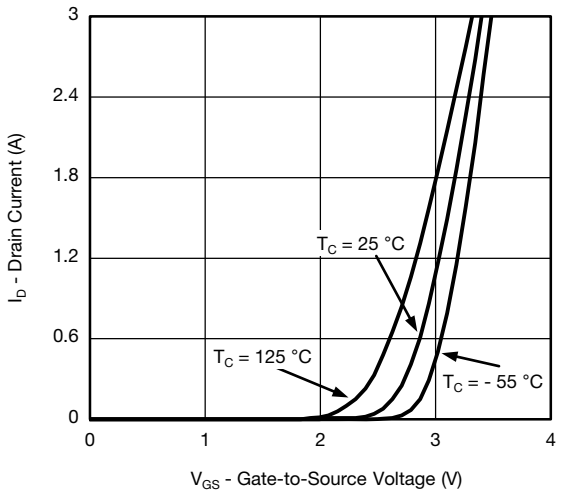
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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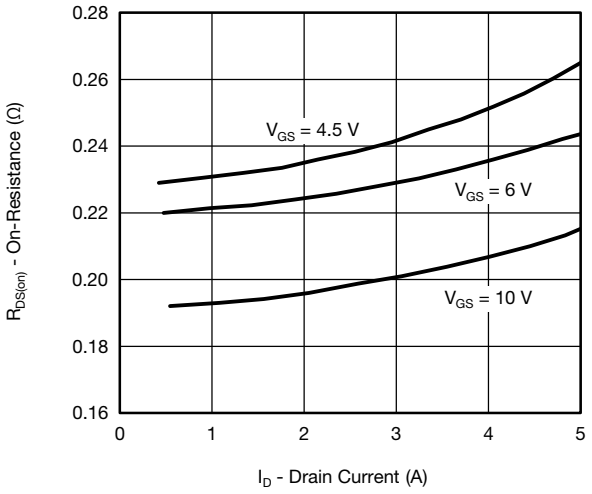
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



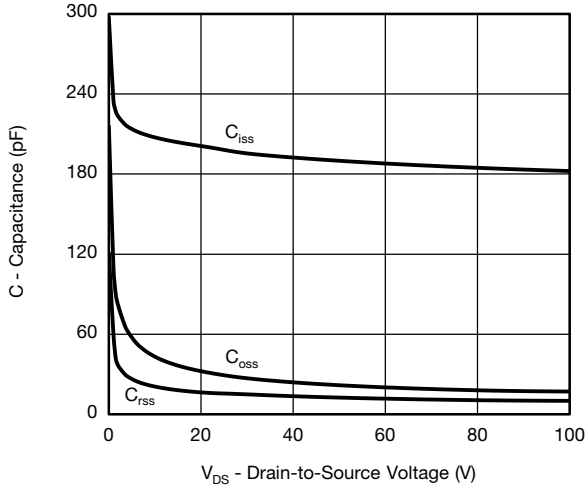
Output Characteristics



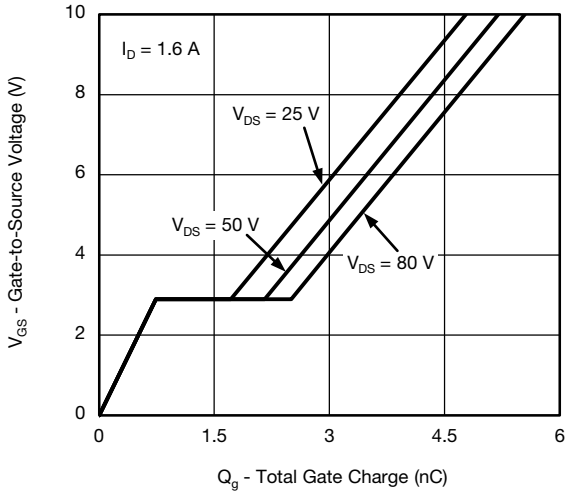
Transfer Characteristics



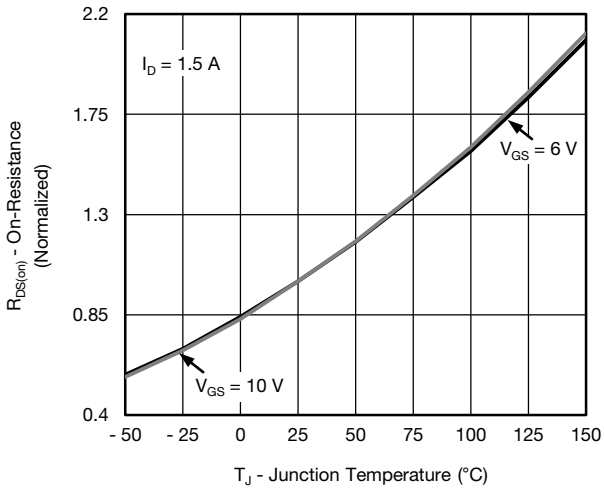
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



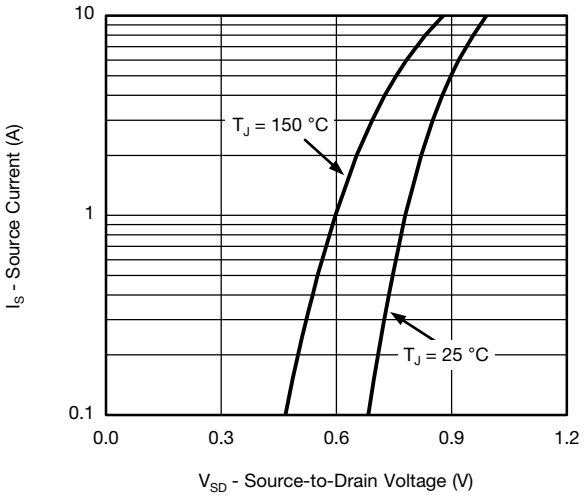
Gate Charge



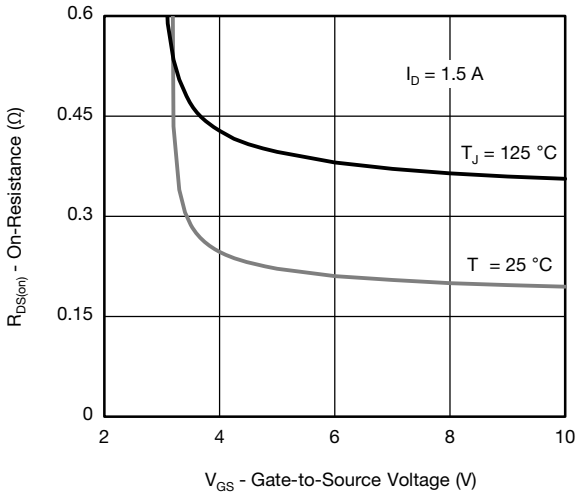
On-Resistance vs. Junction Temperature

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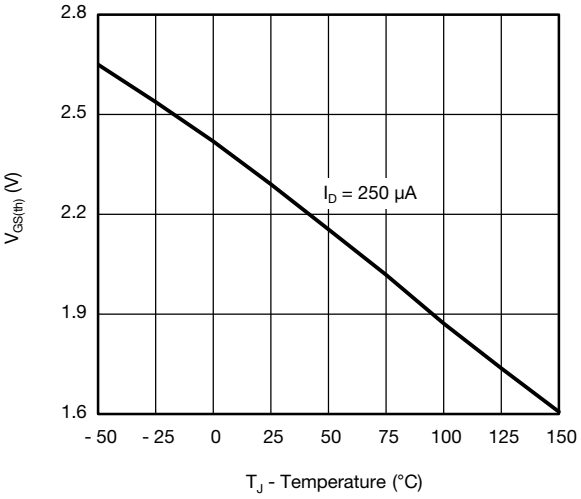
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



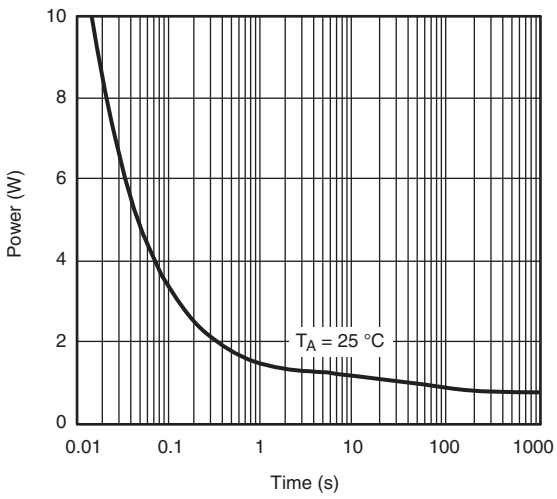
Source-Drain Diode Forward Voltage



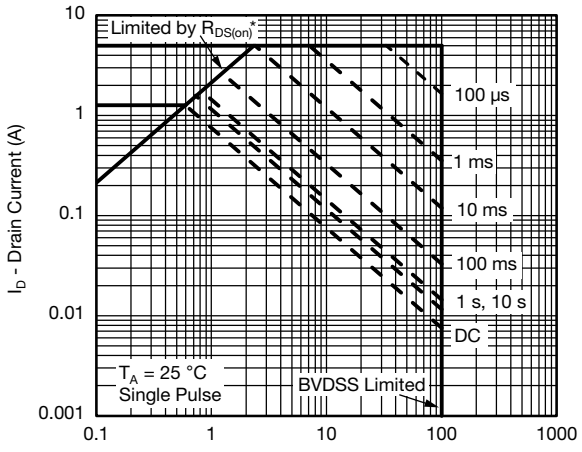
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

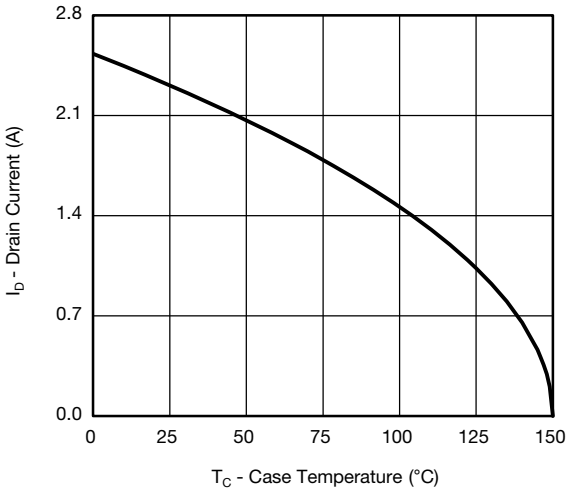
Safe Operating Area

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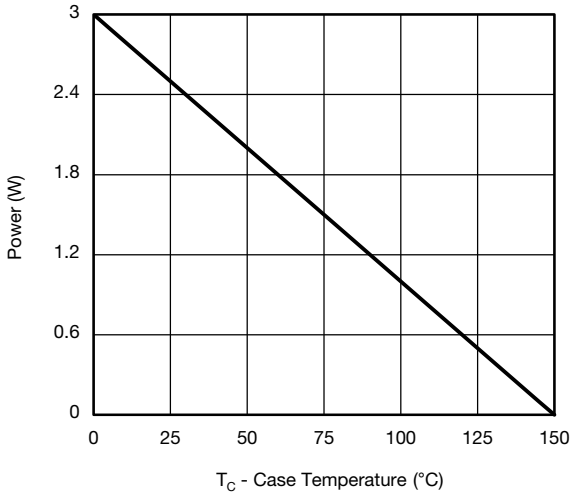
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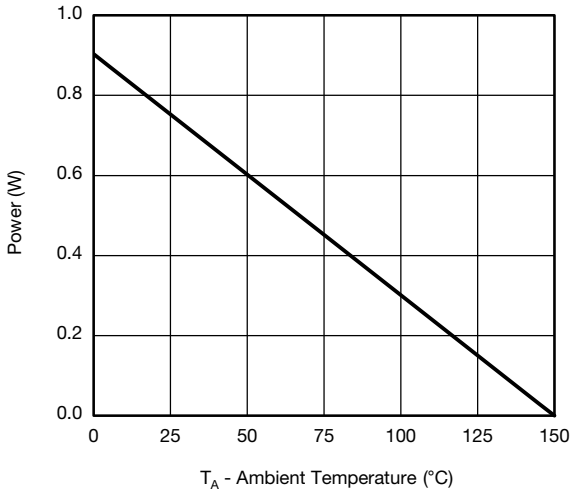
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*



Power, Junction-to-Foot

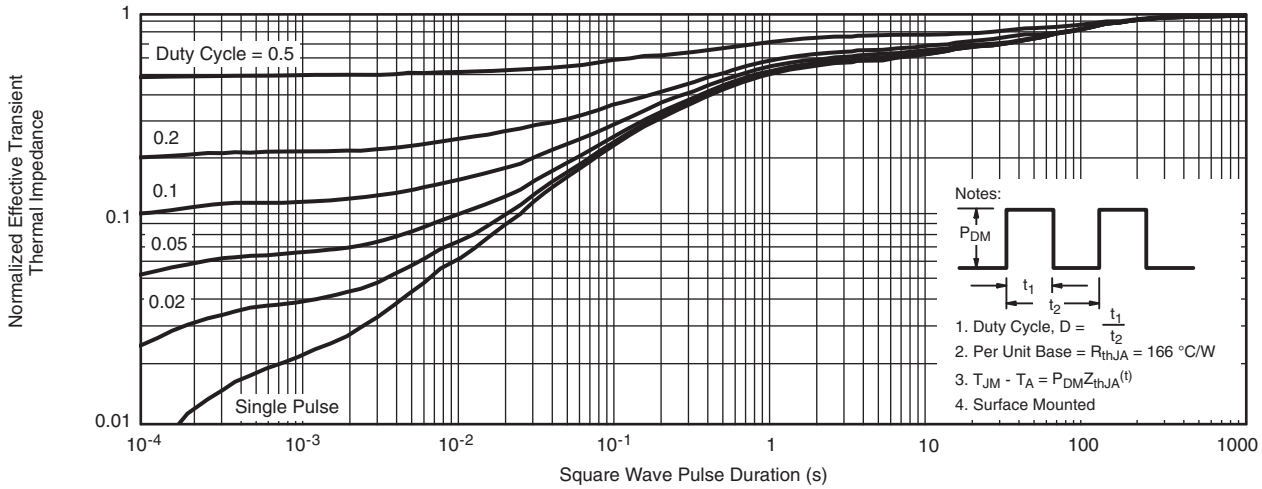


Power, Junction-to-Ambient

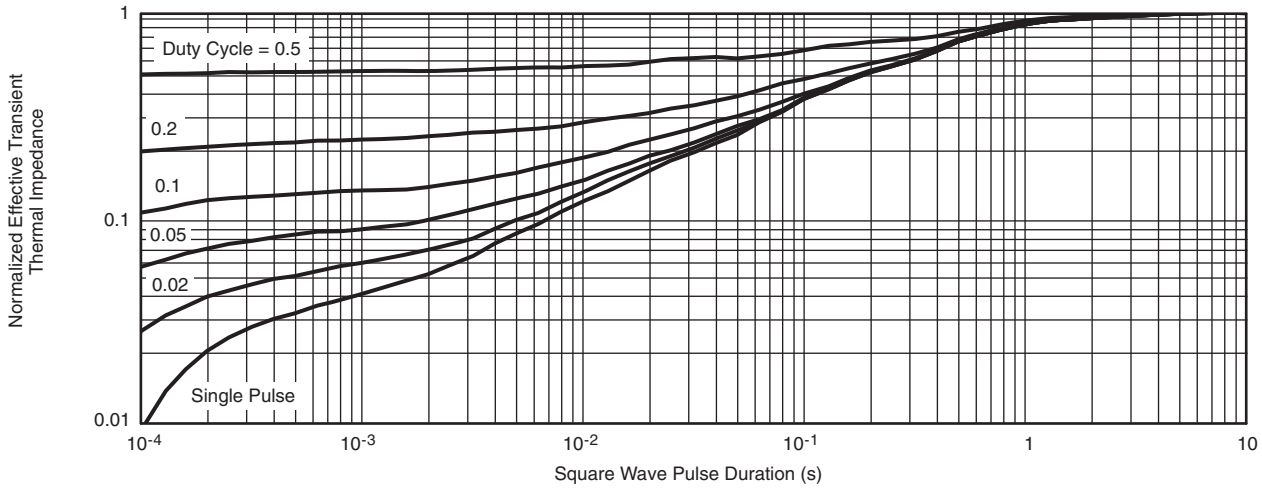
* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

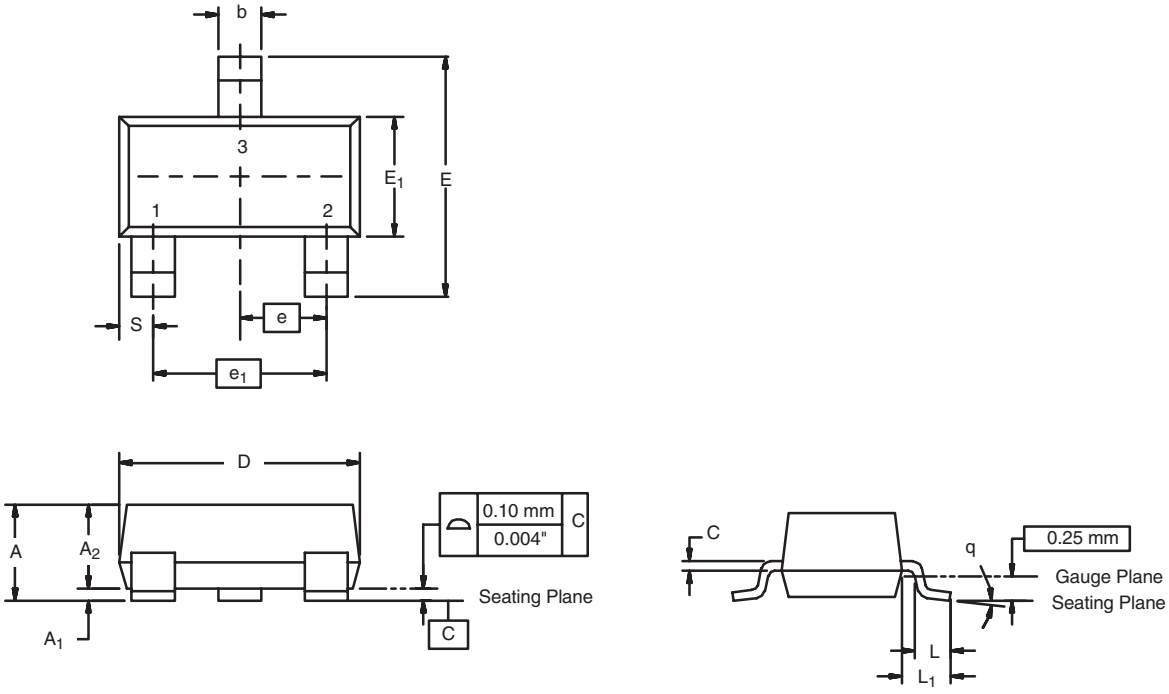


Normalized Thermal Transient Impedance, Junction-to-Foot

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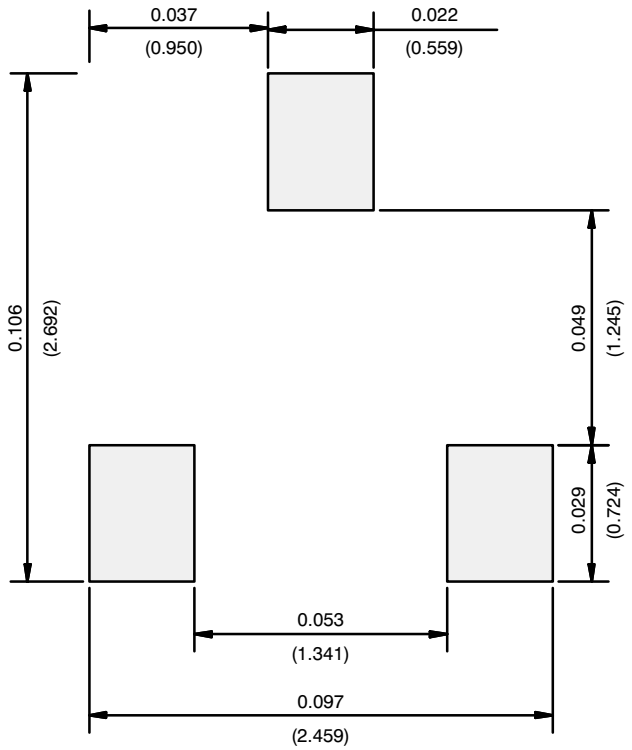
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SOT-23 (TO-236): 3-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A_1	0.01	0.10	0.0004	0.004
A_2	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E_1	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e_1	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L_1	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°
ECN: S-03946-Rev. K, 09-Jul-01 DWG: 5479				

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE

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